

7/15/05


ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

**Title of
Invention**

Bond Pad Structure Comprising Multiple Bond Pads with metal
Overlap

Application Number : 09/927675 

Confirmation Number: 6524

First Named Applicant: Guy Perry

Attorney Docket Number: MTI-31471

Art Unit: 2815

Examiner: Chris C Chu

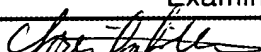
Search string: (4184909 or 5292624 or 4721689).pn

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
C.C.	1	4184909	1980-01-22	Chang et al.		438	624
C.C.	2	5292624	1994-03-08	Wei		430	313
C.C.	3	4721689	1988-01-26	Chaloux et al.		438	618

Signature

Examiner Name	Date
	8/2/05